

# Specification of Thermoelectric Module

## TEC1-07108

### Description

The 71 couples, 30 mm × 30 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

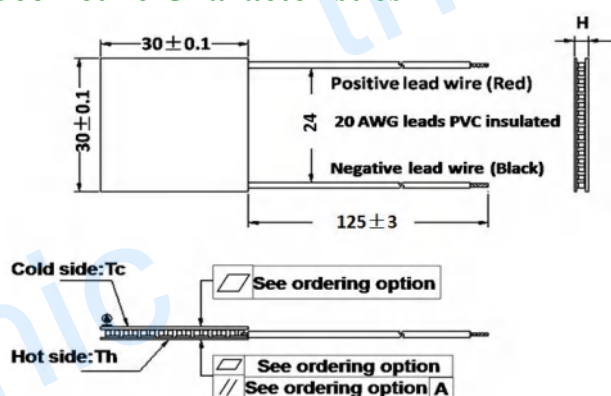
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	8.9	9.6	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	8.0	8.0	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	46.6	48.9	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	0.86	0.94	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.5±0.1	0:0.07/0.07	125±3/Specify
TF	1:3.5±0.03	1:0.025/0.025	125±3/Specify

Eg. TF01: Thickness 3.5 ± 0.1 (mm) and Flatness 0.025 / 0.025 (mm)

### Manufacturing Options

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)
2. T200: CuAgSn (Tmelt = 217°C)
3. T240: SbSn (Tmelt = 240°C)

#### B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant

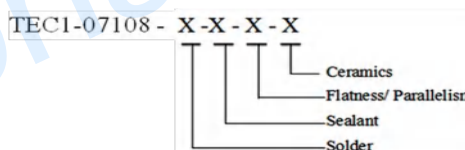
#### C. Ceramics:

1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)
2. Aluminum Nitride (AlN)

#### D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized

### Naming for the Module



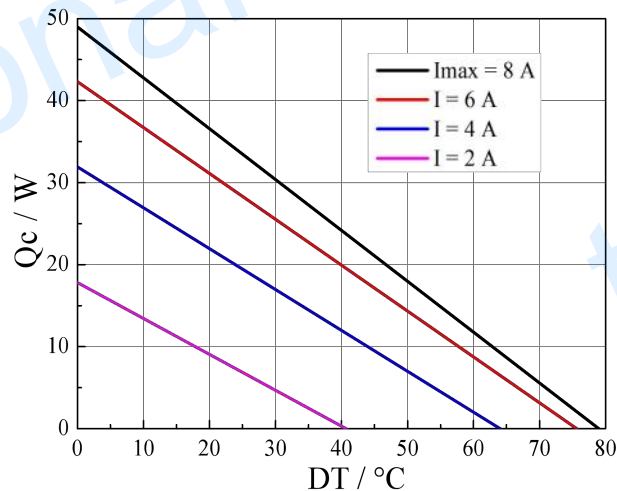
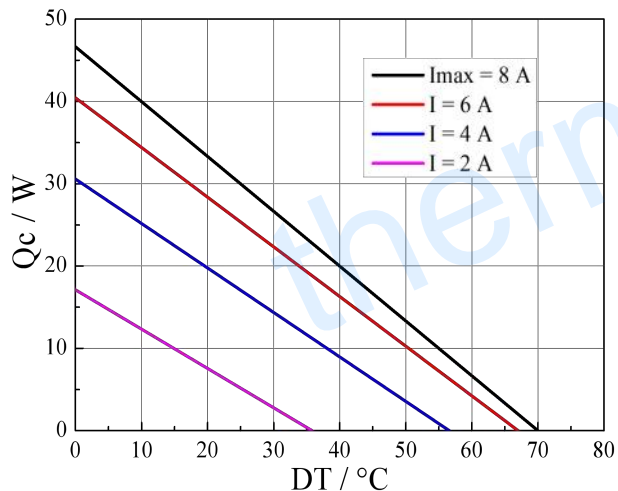
TEC1-07108-T100-NS-TF01-AIO  
 T100: BiSn (Tmelt=138°C)  
 NS: No sealing  
 AIO: Alumina white 96%  
 TF01: Thickness ± 0.1 (mm) and Flatness/Parallelism 0.025/0.025(mm)

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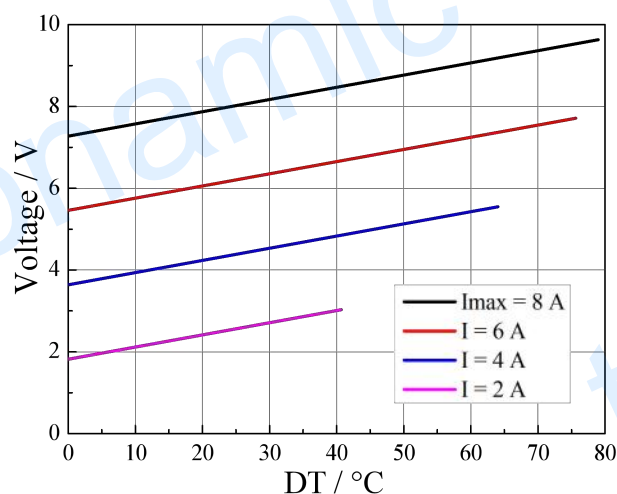
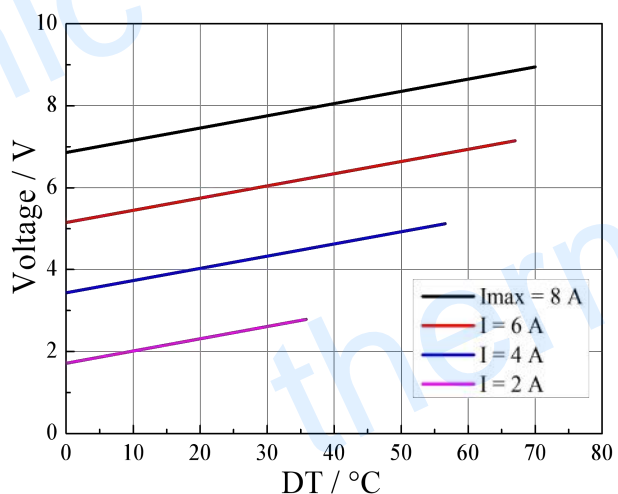
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## Performance Curves at $T_h=27^\circ\text{C}$

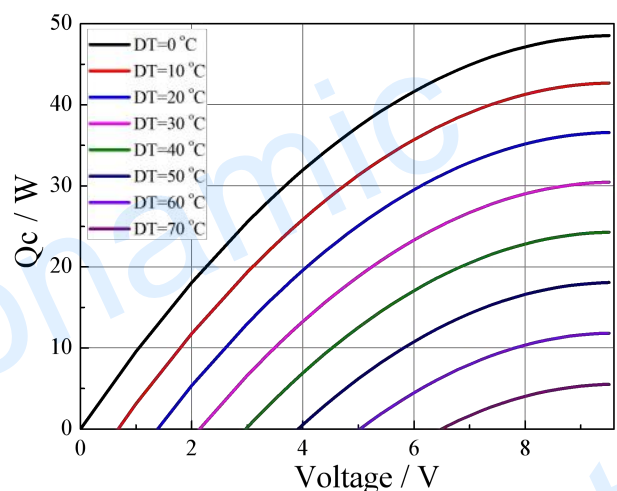
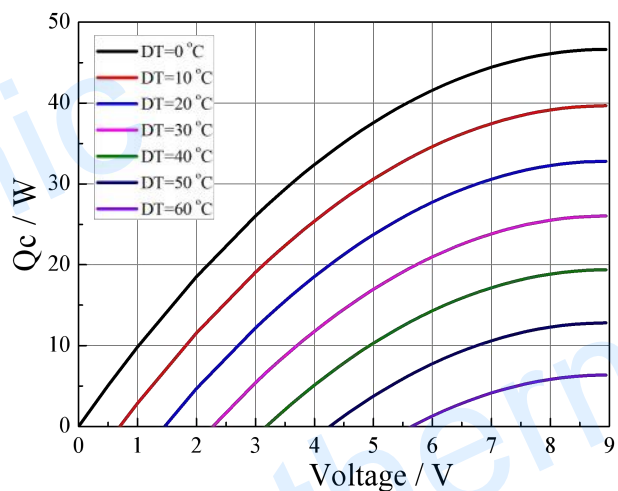
## Performance Curves at $T_h=50^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

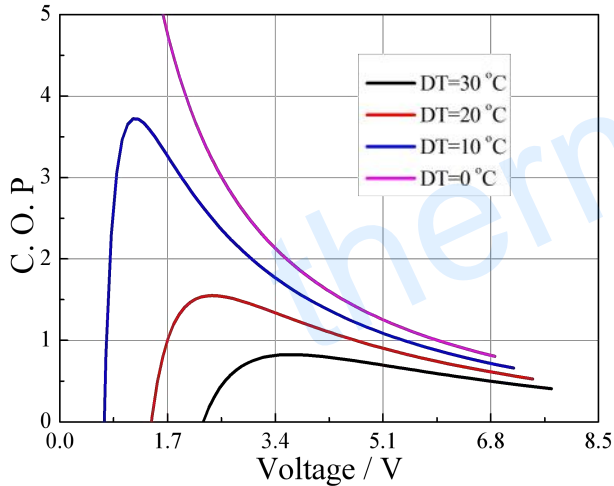


Standard Performance Graph  $Q_c = f(V)$

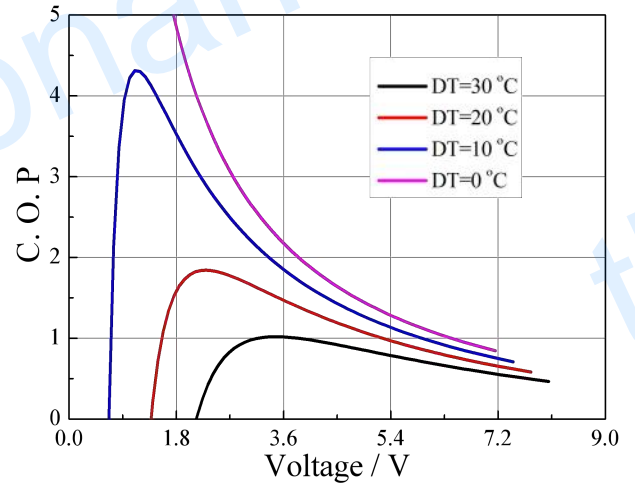
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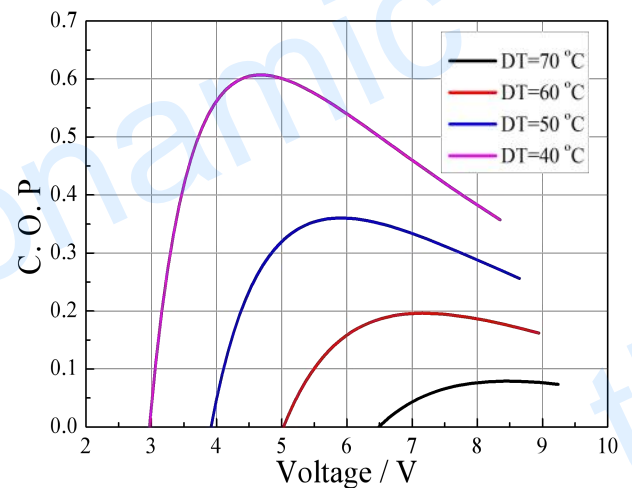
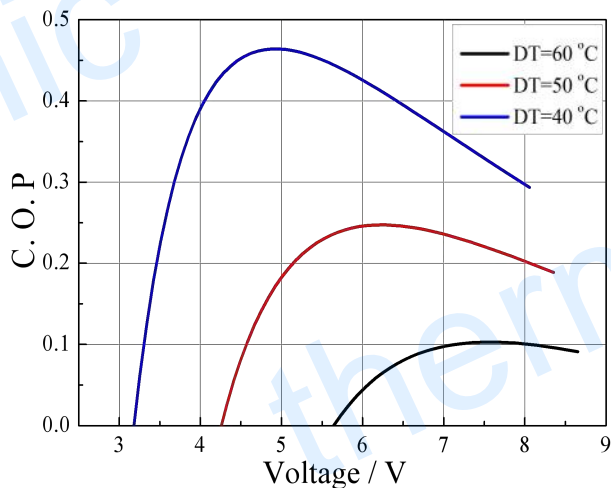
### Performance Curves at Th=27 °C



### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.